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Kind regards,

Team Nexperia
1. Product profile

1.1 General description

LED driver consisting of resistor-equipped PNP transistor with two diodes on one chip in an SOT457 (SC-74) plastic package.

1.2 Features and benefits

- Stabilized output current of 10 mA
- High current accuracy at supply voltage variation
- Low voltage overhead of 1.4 V
- Qualified according to AEC-Q101
- Reduces component count and board space
- High power dissipation of 750 mW
- Stabilized output current adjustable up to 65 mA when an external resistor is used

1.3 Applications

- Constant current LED driver
- Generic constant current source
- Automotive applications

1.4 Quick reference data

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>I&lt;sub&gt;out&lt;/sub&gt;</td>
<td>stabilized output current</td>
<td>V&lt;sub&gt;S&lt;/sub&gt; = 10 V; V&lt;sub&gt;out&lt;/sub&gt; = 8.6 V</td>
<td>8.5</td>
<td>10</td>
<td>11.5</td>
<td>mA</td>
</tr>
<tr>
<td>V&lt;sub&gt;S&lt;/sub&gt;</td>
<td>supply voltage</td>
<td></td>
<td>-</td>
<td>-</td>
<td>40</td>
<td>V</td>
</tr>
</tbody>
</table>
2. Pinning information

<table>
<thead>
<tr>
<th>Pin</th>
<th>Symbol</th>
<th>Description</th>
<th>Simplified outline</th>
<th>Graphic symbol</th>
</tr>
</thead>
<tbody>
<tr>
<td>1</td>
<td>GND</td>
<td>ground</td>
<td></td>
<td></td>
</tr>
<tr>
<td>2</td>
<td>IOUT</td>
<td>output current</td>
<td></td>
<td></td>
</tr>
<tr>
<td>3</td>
<td>IOUT</td>
<td>output current</td>
<td></td>
<td></td>
</tr>
<tr>
<td>4</td>
<td>VS</td>
<td>supply voltage</td>
<td></td>
<td></td>
</tr>
<tr>
<td>5</td>
<td>IOUT</td>
<td>output current</td>
<td></td>
<td></td>
</tr>
<tr>
<td>6</td>
<td>REXT</td>
<td>external resistor</td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

3. Ordering information

<table>
<thead>
<tr>
<th>Type number</th>
<th>Package</th>
<th>Name</th>
<th>Description</th>
<th>Version</th>
</tr>
</thead>
<tbody>
<tr>
<td>NCR401U</td>
<td>SC-74 (TSOP6)</td>
<td>plastic</td>
<td>surface-mounted package; 6 leads</td>
<td>SOT457</td>
</tr>
</tbody>
</table>

4. Marking

<table>
<thead>
<tr>
<th>Type number</th>
<th>Marking code</th>
</tr>
</thead>
<tbody>
<tr>
<td>NCR401U</td>
<td>DA</td>
</tr>
</tbody>
</table>
5. Limiting values

Table 5. Limiting values
In accordance with the Absolute Maximum Rating System (IEC 60134).

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$I_{out}$</td>
<td>stabilized output current if external resistor is used</td>
<td>-</td>
<td>65</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>$V_S$</td>
<td>supply voltage</td>
<td>-</td>
<td>40</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>$V_{out}$</td>
<td>output voltage</td>
<td>$V_S = 40$ V</td>
<td>-</td>
<td>38</td>
<td>V</td>
</tr>
<tr>
<td>$V_R$</td>
<td>reverse voltage</td>
<td>[1]</td>
<td>0.5</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>$P_{tot}$</td>
<td>total power dissipation</td>
<td>$T_{amb} \leq 25^\circ$C</td>
<td>[2]</td>
<td>-</td>
<td>475</td>
</tr>
<tr>
<td>&amp;</td>
<td></td>
<td>$T_{amb} \leq 25^\circ$C</td>
<td>[3]</td>
<td>-</td>
<td>650</td>
</tr>
<tr>
<td>&amp;</td>
<td></td>
<td>$T_{amb} \leq 25^\circ$C</td>
<td>[4]</td>
<td>-</td>
<td>750</td>
</tr>
<tr>
<td>&amp;</td>
<td></td>
<td>$T_{amb} \leq 25^\circ$C</td>
<td>[5]</td>
<td>-</td>
<td>1100</td>
</tr>
<tr>
<td>$T_J$</td>
<td>junction temperature</td>
<td>-</td>
<td>150</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>$T_{amb}$</td>
<td>ambient temperature</td>
<td>-55</td>
<td>+150</td>
<td>°C</td>
<td></td>
</tr>
<tr>
<td>$T_{stg}$</td>
<td>storage temperature</td>
<td>-65</td>
<td>+150</td>
<td>°C</td>
<td></td>
</tr>
</tbody>
</table>

[1] Between all terminals.
[3] Device mounted on an FR4 PCB; single-sided copper; tin-plated and mounting pad for output 1 cm².
[5] Device mounted on an FR4 PCB; 4-layer copper; tin-plated and mounting pad for output 1 cm².

Fig 1. Power derating curve

(1) FR4 PCB, 4-layer copper; standard footprint.
(2) FR4 PCB, single-sided copper; standard footprint.
6. Thermal characteristics

Table 6. Thermal characteristics

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>$R_{th(j-a)}$</td>
<td>thermal resistance from junction to ambient</td>
<td>in free air</td>
<td>[1]</td>
<td>-</td>
<td>265</td>
<td>K/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[2]</td>
<td>-</td>
<td>190</td>
<td>K/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[3]</td>
<td>-</td>
<td>165</td>
<td>K/W</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td>[4]</td>
<td>-</td>
<td>115</td>
<td>K/W</td>
</tr>
</tbody>
</table>

$R_{th(j-sp)}$ thermal resistance from junction to solder point

- (K/W)

[2] Device mounted on an FR4 PCB; single-sided copper; tin-plated and mounting pad for output 1 cm².
[3] Device mounted on an FR4 PCB; 4-layer copper; tin-plated and standard footprint.
[4] Device mounted on an FR4 PCB; 4-layer copper; tin-plated and mounting pad for output 1 cm².

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values
Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

FR4 PCB, 4-layer copper, standard footprint
7. Characteristics

Table 7. Characteristics

\( T_{\text{amb}} = 25 \, ^\circ C; \) pulse test: \( t_p \leq 300 \, \mu s; \) \( \delta = 0.02; \) unless otherwise specified.

<table>
<thead>
<tr>
<th>Symbol</th>
<th>Parameter</th>
<th>Conditions</th>
<th>Min</th>
<th>Typ</th>
<th>Max</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>I_{out}</td>
<td>stabilized output current V_S = 10 V; V_{out} = 8.6 V</td>
<td>8.5</td>
<td>10</td>
<td>11.5</td>
<td>mA</td>
<td></td>
</tr>
<tr>
<td>I_{GND}</td>
<td>ground current V_S = 10 V; I_{out} = 0 A</td>
<td>340</td>
<td>420</td>
<td>500</td>
<td>\mu A</td>
<td></td>
</tr>
<tr>
<td>R_{int}</td>
<td>internal resistance I_{R_{int}} = 10 mA</td>
<td>75</td>
<td>88</td>
<td>101</td>
<td>\Omega</td>
<td></td>
</tr>
<tr>
<td>V_{R_{int}}</td>
<td>voltage drop at internal resistance I_{out} = 10 mA</td>
<td>-</td>
<td>0.88</td>
<td>-</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>V_{S_{min}}</td>
<td>lowest sufficient supply voltage overhead V_S - V_{out}</td>
<td>I_{out} = 8.5 mA</td>
<td>-</td>
<td>1.4</td>
<td>V</td>
<td></td>
</tr>
<tr>
<td>\Delta I_{out} / (I_{out} \times \Delta T_{amb})</td>
<td>stabilized output current change over ambient temperature V_S = 10 V; V_{out} = 8.6 V</td>
<td>-</td>
<td>-0.3</td>
<td>-</td>
<td>%/K</td>
<td></td>
</tr>
<tr>
<td>\Delta I_{out} / (I_{out} \times \Delta V_S)</td>
<td>stabilized output current change over supply voltage V_S = 10 V; V_S - V_{out} = 1.4 V</td>
<td>-</td>
<td>0.8</td>
<td>-</td>
<td>%/V</td>
<td></td>
</tr>
</tbody>
</table>

\( V_S - V_{out} = 1.4 \, V; \) \( T_{\text{amb}} = 25 \, ^\circ C \)

Fig 4. Output current as a function of supply voltage; typical values

Fig 5. Ground current as a function of supply voltage; typical values
Fig 6. Output current as a function of supply voltage; typical values

\[ V_S - V_{out} = 1.4 \text{ V} \text{ or } 2 \text{ V} \]

\( R_{ext} = \text{open} \)  \( T_{amb} = 25 \degree \text{C} \)

Fig 7. Output current as a function of supply voltage; typical values

\[ V_S - V_{out} = 1.4 \text{ V}; R_{ext} = \text{open} \]

(1)  \( T_{amb} = -40 \degree \text{C} \)
(2)  \( T_{amb} = +25 \degree \text{C} \)
(3)  \( T_{amb} = +80 \degree \text{C} \)
(4)  \( T_{amb} = +150 \degree \text{C} \)

Fig 8. Output current as a function of external resistor; typical values

\[ V_S = 10 \text{ V}; V_{out} = 8.6 \text{ V} \]

(1)  \( T_{amb} = -40 \degree \text{C} \)
(2)  \( T_{amb} = +25 \degree \text{C} \)
(3)  \( T_{amb} = +85 \degree \text{C} \)
(4)  \( T_{amb} = +150 \degree \text{C} \)
8. Application information

Figure 9 shows a typical application circuit for an LED driver. The constant current ensures a constant LED brightness. The output current can be adjusted between 10 mA and 65 mA by connecting an external resistor $R_{\text{ext}}$. Figure 8 gives a first indication for choosing the external resistor $R_{\text{ext}}$. The output current slightly decreases when the power load at LED driver increases. This effect is due to the self heating of the device and the negative thermal coefficient of the output current.

![Fig 9. LED driver application diagram](image)

The output can be switched ON and OFF by connecting a Resistor-Equipped Transistor (RET), e.g. PDTC124XU; see Figure 10.

![Fig 10. Switching the current ON/OFF; application diagram](image)
9. Test information

9.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.
10. Package outline

Plastic surface-mounted package (TSOP6); 6 leads

**Dimensions (mm are the original dimensions)**

<table>
<thead>
<tr>
<th>UNIT</th>
<th>A</th>
<th>A₁</th>
<th>bₚ</th>
<th>c</th>
<th>D</th>
<th>E</th>
<th>e</th>
<th>Hₑ</th>
<th>Lₚ</th>
<th>Q</th>
<th>v</th>
<th>w</th>
<th>y</th>
</tr>
</thead>
<tbody>
<tr>
<td>mm</td>
<td>1.1</td>
<td>0.1</td>
<td>0.40</td>
<td>0.26</td>
<td>3.1</td>
<td>1.7</td>
<td>0.95</td>
<td>3.0</td>
<td>0.6</td>
<td>0.33</td>
<td>0.2</td>
<td>0.2</td>
<td>0.1</td>
</tr>
<tr>
<td></td>
<td>0.9</td>
<td>0.013</td>
<td>0.25</td>
<td>0.10</td>
<td>2.7</td>
<td>1.3</td>
<td></td>
<td>2.5</td>
<td>0.2</td>
<td>0.23</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

**Fig 11. Package outline SOT457 (SC-74)**
11. Soldering

**Fig 12.** Reflow soldering footprint for SOT457 (SC-74)

**Fig 13.** Wave soldering footprint for SOT457 (SC-74)
### 12. Revision history

Table 8. Revision history

<table>
<thead>
<tr>
<th>Document ID</th>
<th>Release date</th>
<th>Data sheet status</th>
<th>Change notice</th>
<th>Supersedes</th>
</tr>
</thead>
<tbody>
<tr>
<td>NCR401U v.1</td>
<td>20140220</td>
<td>Product data sheet</td>
<td>-</td>
<td>-</td>
</tr>
</tbody>
</table>
13. Legal information

13.1 Data sheet status

<table>
<thead>
<tr>
<th>Document status[1][3]</th>
<th>Product status[1][3]</th>
<th>Definition</th>
</tr>
</thead>
<tbody>
<tr>
<td>Objective [short] data sheet</td>
<td>Development</td>
<td>This document contains data from the objective specification for product development.</td>
</tr>
<tr>
<td>Preliminary [short] data sheet</td>
<td>Qualification</td>
<td>This document contains data from the preliminary specification.</td>
</tr>
<tr>
<td>Product [short] data sheet</td>
<td>Production</td>
<td>This document contains the product specification.</td>
</tr>
</tbody>
</table>

[1] Please consult the most recently issued document before initiating or completing a design.
[2] The term ‘short data sheet’ is explained in section “Definitions”.
[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

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